



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



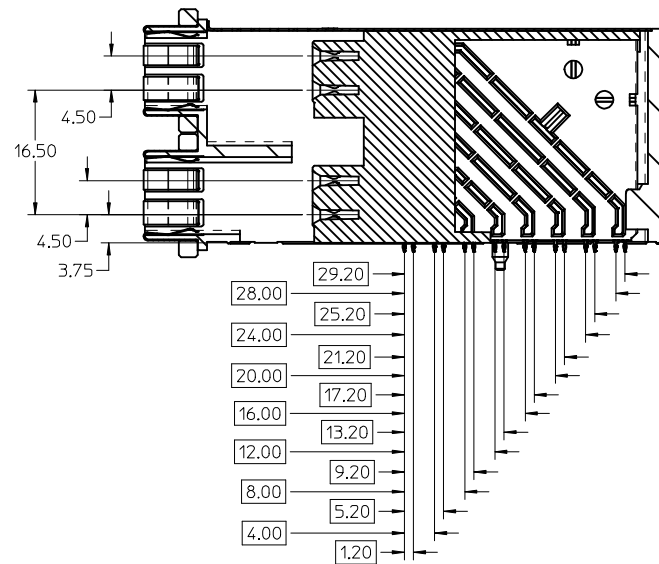
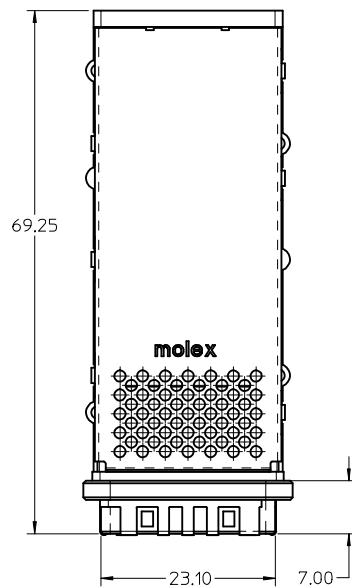
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

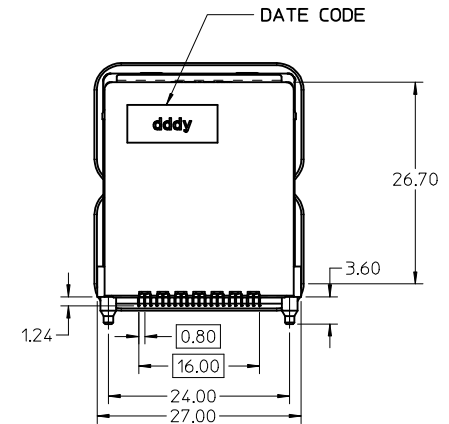
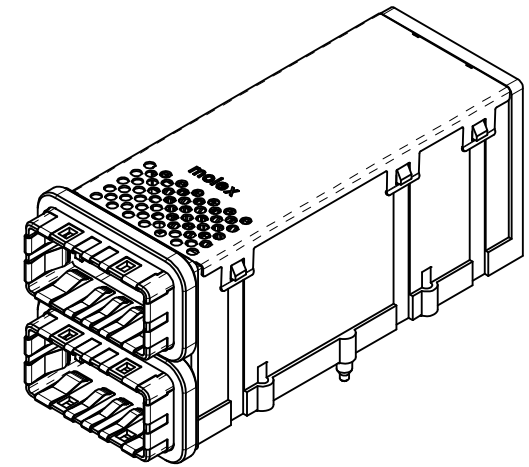
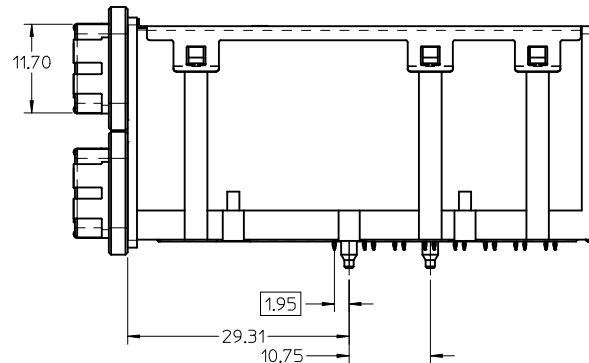
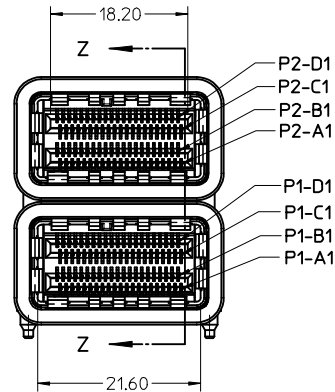
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





SECTION Z-Z



NOTES:

1. MATERIALS:

CONNECTOR HOUSING: HIGH TEMPERATURE THERMOPLASTIC
GLASS FILLED, UL94V-0
COLOR: BLACK

EMI HOUSING: DIE CAST ALLOY, NICKEL PLATED FINISH

TERMINALS: COPPER ALLOY

COVER: STAINLESS STEEL ALLOY

EMI GASKET: CONDUCTIVE POLYMER

2. PLATING:

CONTACT AREA: 0.76mm MIN. GOLD OVER 2.54mm MIN. NICKEL

COMPLIANT AREA:

OPTION 1: COMPLIANT AREA: 0.76-1.52mm TIN LEAD (90/10) OVER 1.27mm MIN. NICKEL

OPTION 2: COMPLIANT AREA: 0.76-1.52mm TIN OVER 1.27mm MIN. NICKEL

3. PACKAGING SPECIFICATION: TRAY PACK PER PK-76024-001

4. MOUNTING HARDWARE: M2x8mm CAP SCREWS (NOT SUPPLIED)

5. THIS CONNECTOR IS DESIGNED TO MATE WITH MOLEX CABLE SERIES 111025

6. THIS CONNECTOR IS FOR PASSIVE COPPER CABLES ONLY

NO OPTICAL MODULES OR ACTIVE COPPER CABLES

CHG NOTE&S SHT2
EC NO: UCP2013-2120
DRAWING PRATT 2012/12/13
CHKD: MBANAKIS 2012/12/13
APPR: MBANAKIS 2012/12/18

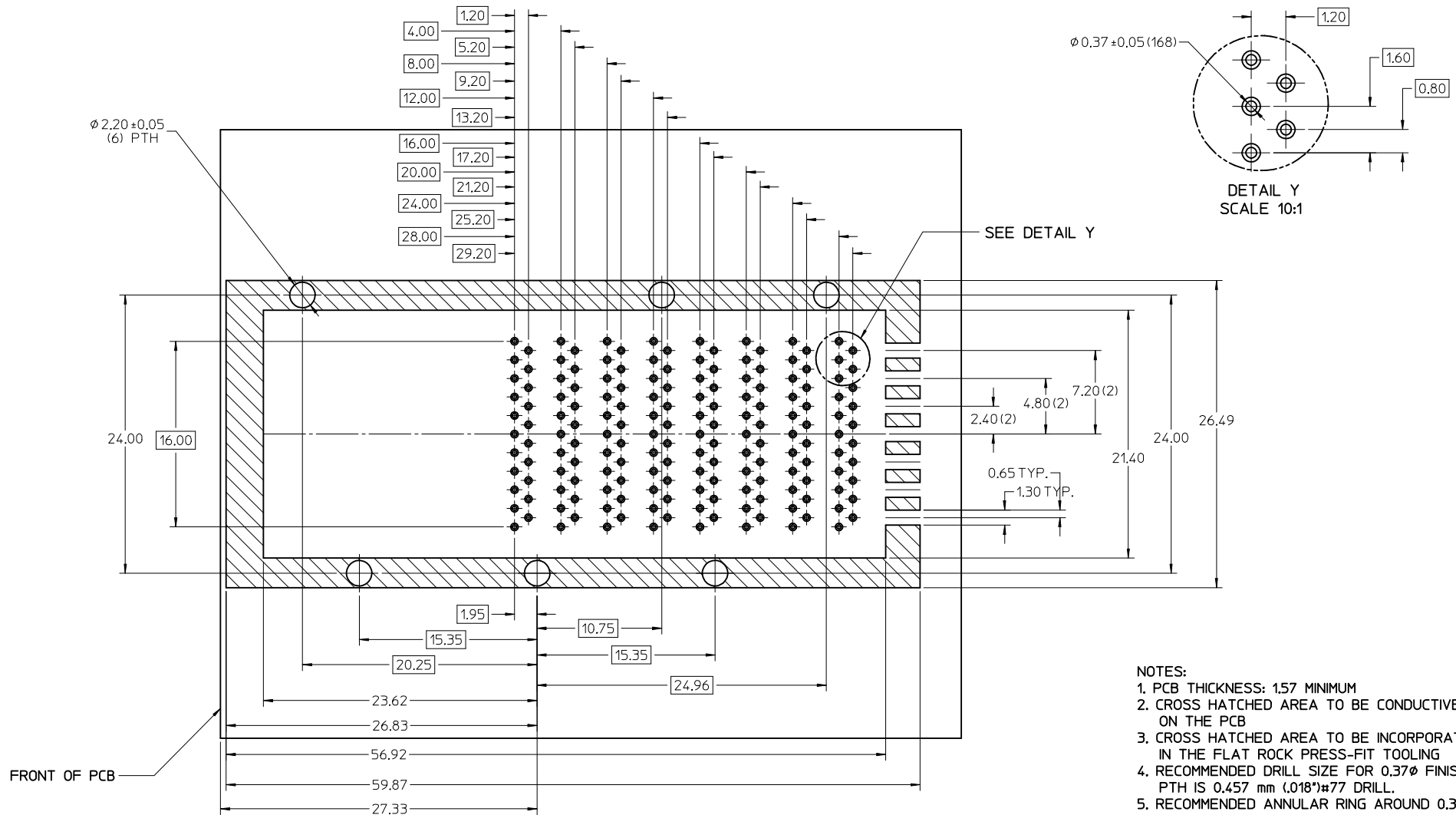
QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)
mm INCH
4 PLACES ± --- ± ---
3 PLACES ± --- ± ---
2 PLACES ± 0.13 ± ---
1 PLACE ± 0.25 ± ---
ANGULAR ± 1/2°
DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY
DRAWN BY DATE
K.LANG 2008/06/12
CHECKED BY DATE
APPROVED BY DATE
M.BANAKIS 2008/07/21
MATERIAL NO.
SEE CHART
SIZE C

SCALE
2:1
DESIGN UNITS
METRIC
THIRD ANGLE PROJECTION
IPASS PLUS HSC 84/84
HIGH SPEED CHANNEL
0.8MM I/O
MOLEX INCORPORATED
DOCUMENT NO.
SD-76024-568
SHEET NO.
1 OF 4
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

RECOMMENDED PCB LAYOUT COMPONENT SIDE SHOWN



NOTES:

1. PCB THICKNESS: 1.57 MINIMUM
2. CROSS HATCHED AREA TO BE CONDUCTIVE ON THE PCB
3. CROSS HATCHED AREA TO BE INCORPORATED IN THE FLAT ROCK PRESS-FIT TOOLING
4. RECOMMENDED DRILL SIZE FOR 0.37φ FINISHED PTH IS 0.457 mm (0.018")#77 DRILL.
5. RECOMMENDED ANNULAR RING AROUND 0.37φ FINISHED PTH IS 0.73φ
6. MINIMUM RECOMMENDED SPACING: 26.50mm

SEE SHEET 1
EC NO: UCP2013-2120
DRAWN: GRATT
CHKD: MBANAKIS
APPR: MBANAKIS

QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± 0.25	± 0.010
3 PLACES	± 0.20	± 0.008
2 PLACES	± 0.13	± 0.005
1 PLACE	± 0.25	± 0.010

ANGULAR ± 1/2°

DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY: K. LANG
DATE: 2008/06/12

CHECKED BY: DATE

APPROVED BY: M. BANAKIS
DATE: 2008/07/21

MATERIAL NO.

SEE SHEET 1

SCALE: 4:1

DESIGN UNITS: METRIC

THIRD ANGLE PROJECTION

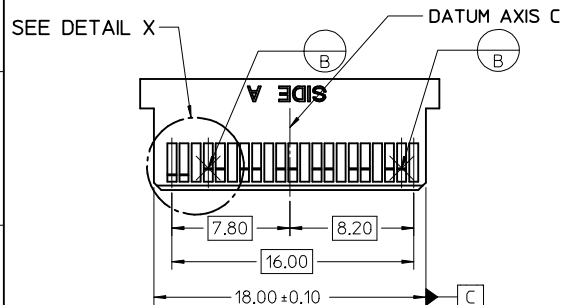
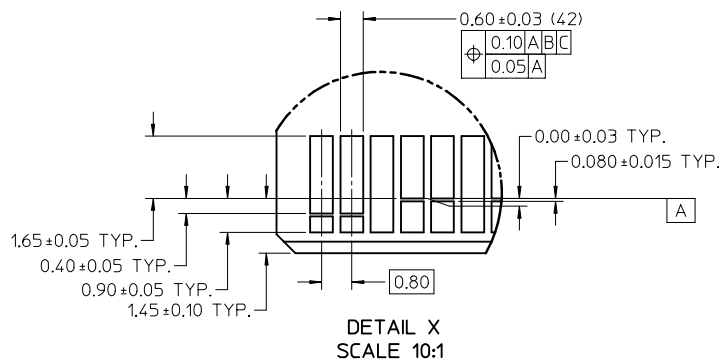
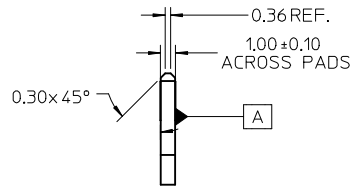
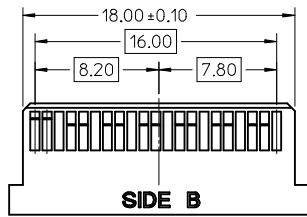
TITLE: IPASS PLUS HSC 84/84
HIGH SPEED CHANNEL
0.8MM I/O

MOLEX INCORPORATED

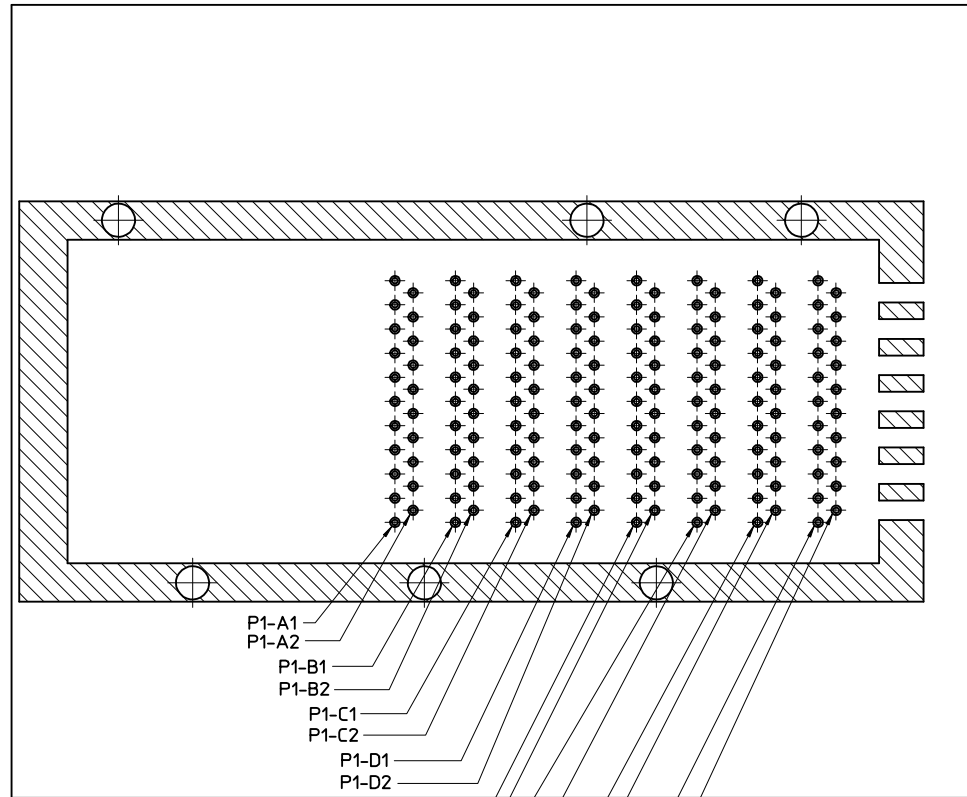
DOCUMENT NO.: SD-76024-568

SHEET NO.: 2 OF 4

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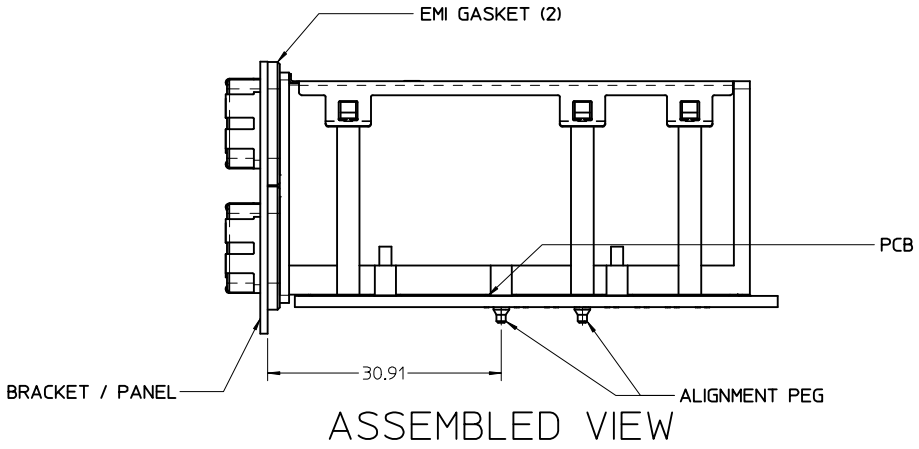
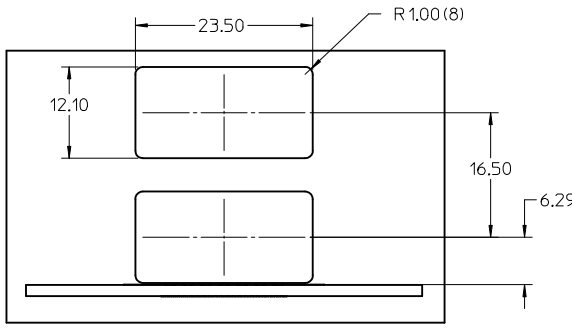


- NOTES:**
- 0.03 MINIMUM KEEPOUT FOR SOLDER MASK AROUND ALL PADS
 - DATUM B TARGETS ARE DEFINED BY THE RESPECTIVE PAD CENTER LINES AND THE LEADING EDGE OF THE TARGET PADS



SEE SHEET 1 EC NO: UCP2013-2120 DRAWN: GPRATT CHKD: MBANAKIS APPR: MBANAKIS F1	2012/12/13 2012/12/13 2012/12/18	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
					mm	INCH	DRAWN BY K. LANG	DATE 2008/06/12	TITLE IPASS PLUS HSC 84/84 HIGH SPEED CHANNEL 0.8MM I/O					
				4 PLACES	± ---	± ---	CHECKED BY	DATE						
				3 PLACES	± ---	± ---	APPROVED BY M. BANAKIS 2008/07/21		MOLEX MOLEX INCORPORATED					
				2 PLACES	± 0.13	± ---								
				1 PLACE	± 0.25	± ---								
				ANGULAR ±1/2°			MATERIAL NO.		DOCUMENT NO.					
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE CHART			SD-76024-568				
							SIZE			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
										SHEET NO. 3 OF 4				

RECOMMENDED PANEL CUT-OUT



SEE SHEET 1 EC NO: UCP2013-2120 2012/12/13 DRAWN:GPRATT CHKD:MBANAKIS 2012/12/13 APPR:MBANAKIS 2012/12/18	REV	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
					mm	INCH	DRAWN BY K.LANG	DATE 2008/06/12	TITLE IPASS PLUS HSC 84/84 HIGH SPEED CHANNEL 0.8MM I/O		
				4 PLACES	± ---	± ---	CHECKED BY				DATE
				3 PLACES	± ---	± ---	APPROVED BY				DATE
				2 PLACES	± 0.13	± ---	M.BANAKIS				2008/07/21
				1 PLACE	± 0.25	± ---	MATERIAL NO.		DOCUMENT NO.		
				ANGULAR ±1/2°		SEE SHEET 1		SD-76024-568			
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
								SHEET NO. 4 OF 4			